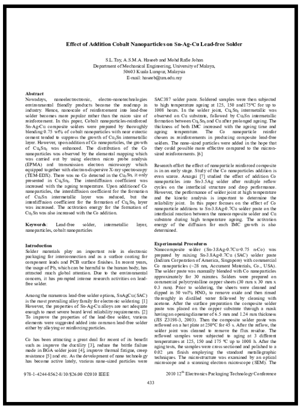
Solder joint technology - materials, properties, and reliability

Springer - American Standard Circuits :: Webinar Review: Solder Joint Reliability With IMS Materials



Description: -

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World War, 1939-1945 -- Regimental histories -- Poland.
Poland. -- Polskie Siły Zbrojne. -- Armia Krajowa. -- Pułk Piechoty, 74 -- Biography.
Poland. -- Polskie Siły Zbrojne. -- Armia Krajowa. -- Pułk Piechoty, 74 -- History.
Poland. -- Wojsko Polskie. -- Górnośląski Pułk Piechoty, 74 -- History.
Metals -- Weldability.
Solder and soldering.
Welded joints -- Reliability.
Welded joints.Solder joint technology - materials, properties, and reliability

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Springer series in materials science -- 92Solder joint technology - materials, properties, and reliability
Notes: Includes bibliographical references and index.
This edition was published in 2007

Tags: #Solder #Joint #Technology: #Materials, #Properties, #and #Reliability #(Springer #Series #in #Materials #Science)

Fatigue Properties and Microstructure of SnAgCu Bi

The results of SnAgCu and SnCu—Bi solder alloys show similar fatigue performance. Science and Technology of Advanced Materials.

Circuits Assembly Online Magazine

The BGA packages were soldered to a 700µm-thick, 30. The effects of the laser and processing parameters on fluxless soldering will be discussed.

Solder Joint Technology: Materials, Properties, and Reliability (Springer Series in Materials Science)

In addition to evaluating the reliability through accelerated tests, it is important to consider the impact of other component layers on the thermomechanical performance of the interface material, both from a material and geometric perspective. This paper will describe recent progress in a research effort to establish a microstructurally-based, constitutive model that predicts TMF deformation to 63Sn-37Pb solder in electronic solder joints up to the crack initiation step.

Fatigue Properties and Microstructure of SnAgCu Bi

There has consequently been a significant effort to develop alternative, environmentally conscious manufacturing technologies that will satisfy this objective.

Solder Joint Reliability : Theory and Applications by John H. Lau (1991, Hardcover) for sale online

This effect can drastically reduce fatigue lifetime. This pervasive dependency on solder has stimulated new interest in applica- tions as well as a more concerted effort to better understand materials properties. To improve solder joint reliability the science of solder joint behavior under

various driving forces must be understood in this book the advanced materials reliability issues related to copper tin reaction and electromigration in solder joints are emphasized and methods to prevent these reliability problems are discussed.

Related Books

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